

Applicant appreciates the courtesies extended to Applicant's representative during the October 4 personal interview with Examiner Graybill. The points discussed during the personal interview are incorporated in the following remarks.

Claims 1, 3, 4, 6, 7, 9, 10 and 12 stand rejected under 35 U.S.C. §102(b) as being anticipated by Thompson (U.S. Patent No. 5,293,067) or in the alternative under 35 U.S.C. §103(a) as being obvious over Thompson or in the alternative under 35 U.S.C. §103(a) as being obvious over Thompson in view of Rostoker (U.S. Patent No. 5,767,580). Applicant respectfully traverses the rejections.

In particular, Applicant respectfully submits that neither Thompson nor Rostoker, individually or in combination, disclose or suggest a substrate for semiconductor apparatus including a substrate main body having a first surface, a second surface and a plurality of through-holes, a plurality of leads formed on the first surface, the plurality of leads extending from a peripheral area towards a central area of the substrate main body, and conduction sections being electrically connected to the leads via the plurality of through-holes, internal surfaces of the through-holes are conductive and connected to the respective leads, and the through-holes are arranged corresponding to the respective leads such that the substrate main body that is cut along predetermined through-holes, allows remaining through-holes connected to the respective leads to define the conduction sections, as recited in independent claim 1 and similarly recited in independent claim 7.

Thompson discloses an integrated circuit chip carrier assembly including a semiconductor device 10 carried to a circuitry pattern 18 on a first side of a circuit carrying substrate 16. As set forth in column 2, lines 61-65, for example, the substrate 16 also contains other circuitry 20 that interconnects pad to the conductive through-holes of vias 22 in the substrate. However, Thompson fails to disclose or suggest the through-holes are arranged corresponding to the respective leads such that the substrate main body that is cut

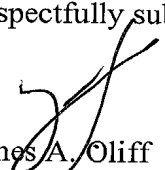
along predetermined through-holes, allows remaining through-holes connected to the respective leads to define the conduction sections.

Rostoker fails to cure the above-noted deficiencies of Thompson. Rostoker discloses in Figure 3A that the bump pad is of a rectangular ring shape.

Accordingly, Applicant respectfully submits that claims 1, 3-4, 6-7 and 9-12 define patentable subject matter. Accordingly, favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned attorney at the telephone number listed below.

Respectfully submitted,


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JAO:YSC/tea

Date: **December 6, 2002**

Attachment:
Appendix

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